

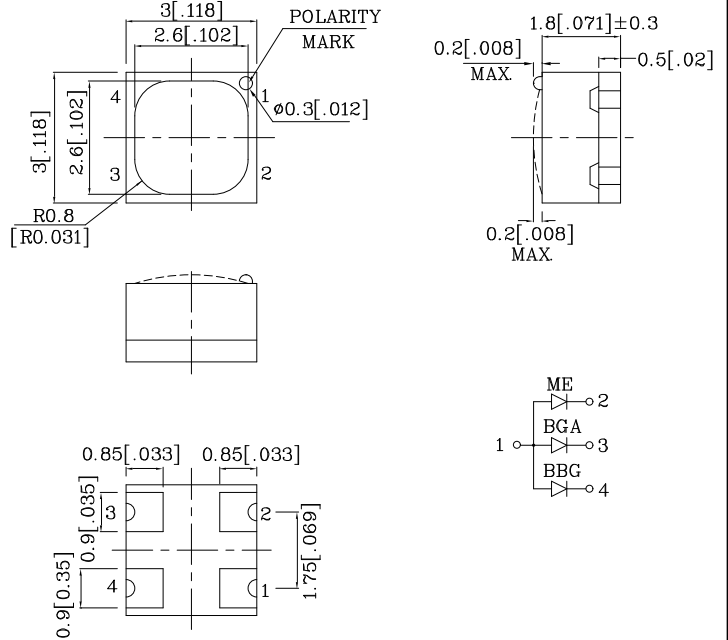
PRELIMINARY SPEC

Features

- LOW POWER CONSUMPTION.
- 3.0mmx3.0mm SMT LED, 1.8mm THICKNESS.
- ONE RED, ONE GREEN AND ONE BLUE CHIPS IN ONE PACKAGE.
- CAN PRODUCE ANY COLOR IN VISIBLE SPECTRUM, INCLUDING WHITE LIGHT.
- PACKAGE : 1000PCS / REEL.
- MOISTURE SENSITIVITY LEVEL : LEVEL 4.
- RoHS COMPLIANT.



ATTENTION
 OBSERVE PRECAUTIONS
 FOR HANDLING
 ELECTROSTATIC
 DISCHARGE
 SENSITIVE
 DEVICES



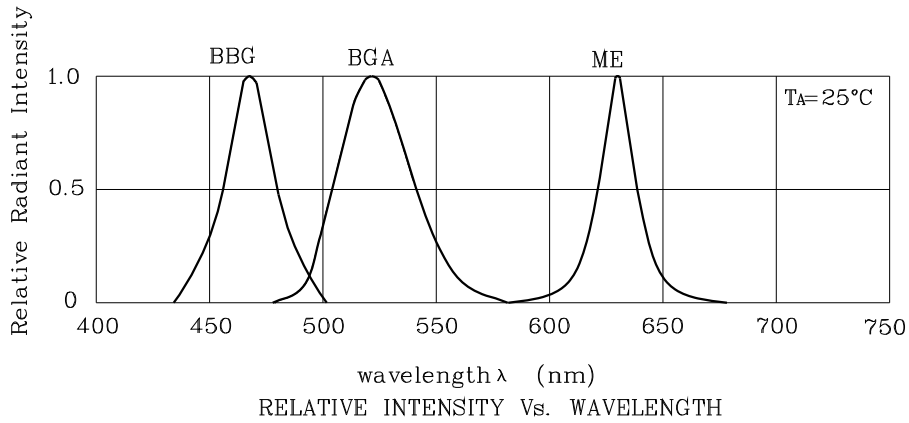
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.2(0.008)$ unless otherwise noted.
3. Specifications are subject to change without notice.

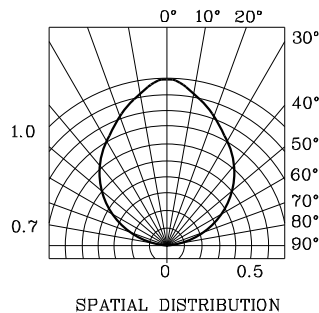
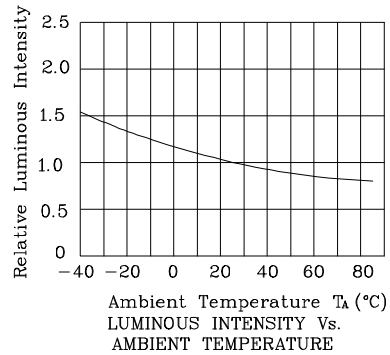
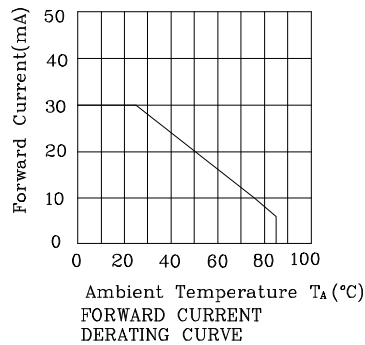
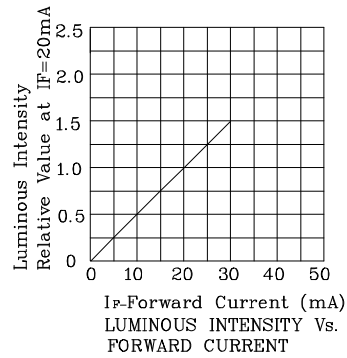
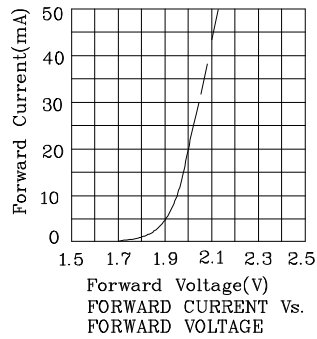
Operating Characteristics ($T_A=25^\circ\text{C}$)		ME (InGa AlP)	BGA (InGa N)	BBG (InGa N)	Unit
Forward Voltage (Typ.) ($I_F=20\text{mA}$)	V_F	2.0	3.2	3.2	V
Forward Voltage (Max.) ($I_F=20\text{mA}$)	V_F	2.5	4.0	4.0	V
Reverse Current (Max.) ($V_R=5\text{V}$)	I_R	10	10	10	μA
Wavelength Of Peak Emission (Typ.) ($I_F=20\text{mA}$)	λ_P	630	520	468	nm
Wavelength Of Dominant Emission (Typ.) ($I_F=20\text{mA}$)	λ_D	621	525	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) ($I_F=20\text{mA}$)	$\Delta\lambda$	20	35	21	nm
Capacitance (Typ.) ($V_F=0\text{V}$, $f=1\text{MHz}$)	C	25	100	100	pF

Absolute Maximum Ratings ($T_A=25^\circ\text{C}$)		ME (InGa AlP)	BGA (InGa N)	BBG (InGa N)	Unit
Reverse Voltage	V_R	5	5	5	V
Forward Current	I_F	30	30	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i_{FS}	195	100	100	mA
Power Dissipation	P_T	75	120	120	mW
Operating Temperature	T_A	-40 ~ +85			°C
Storage Temperature	T_{stg}	-40 ~ +85			
Electrostatic Discharge Threshold (HBM)	-	1000	1000		V

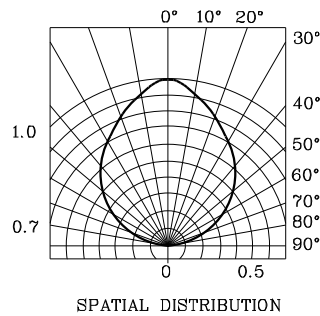
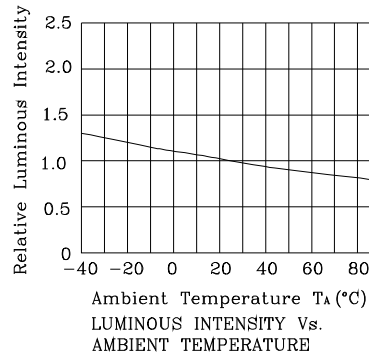
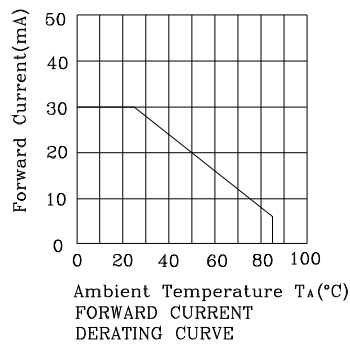
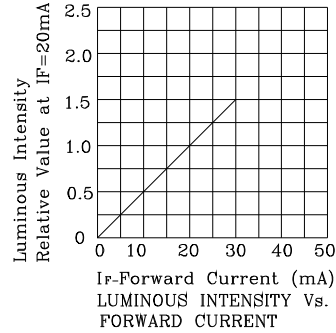
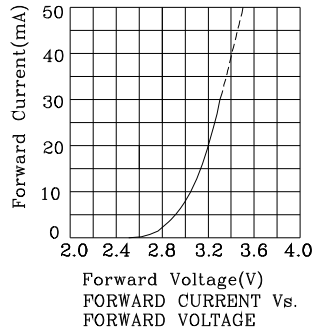
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity ($I_F=20\text{mA}$) mcd		Wavelength nm λ_P	Viewing Angle 2θ 1/2
				min.	typ.		
ZMEBGABBG86W	Red	InGaAlP	Water Clear	180	397	630	100°
	Green	InGaN		110	248	520	
	Blue	InGaN		70	158	468	



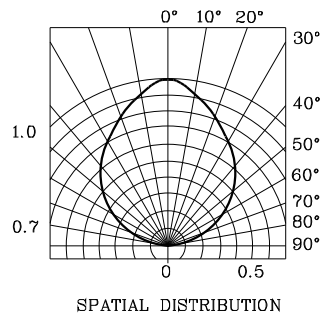
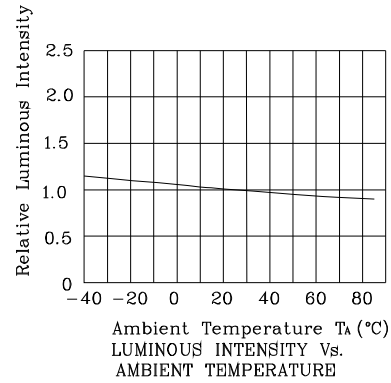
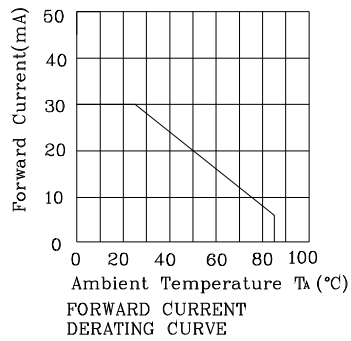
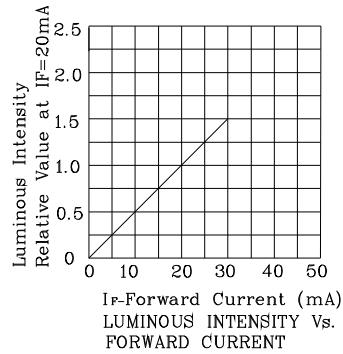
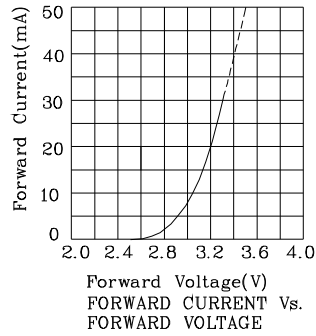
❖ ME



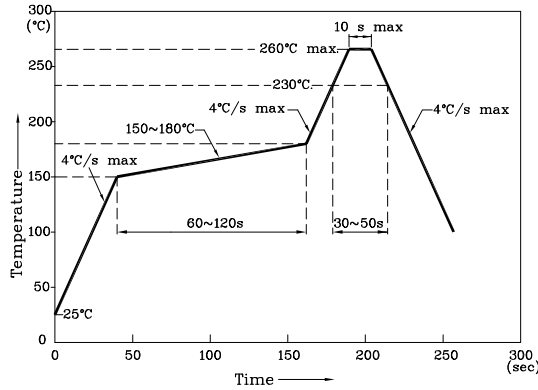
❖ BGA



❖ **BBG**



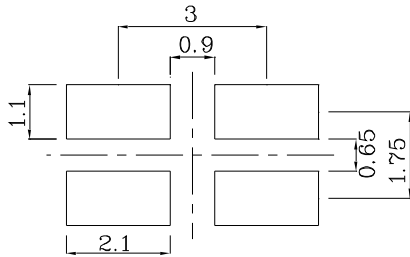
Reflow Soldering Profile For Lead-free SMT Process.



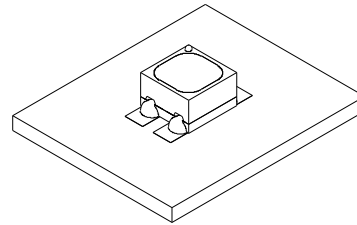
NOTES:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

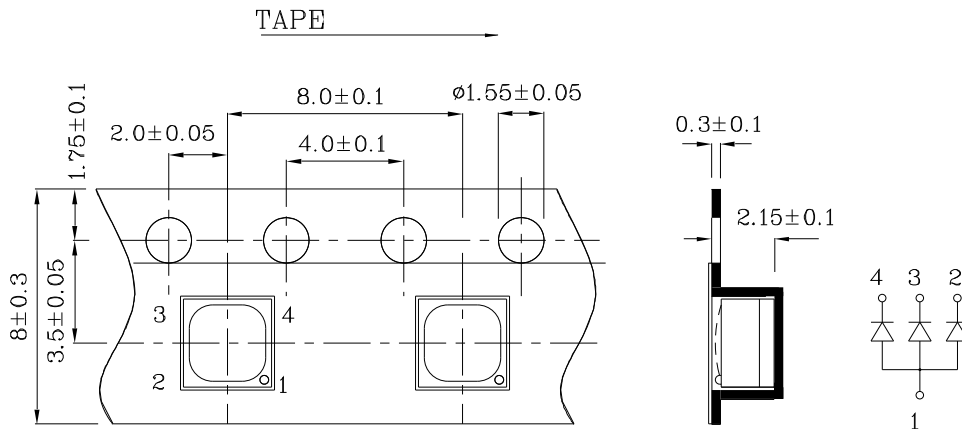
❖ Recommended Soldering Pattern (Units : mm; Tolerance: ±0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

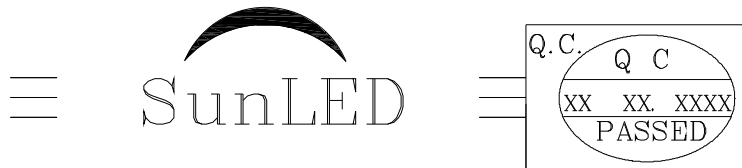
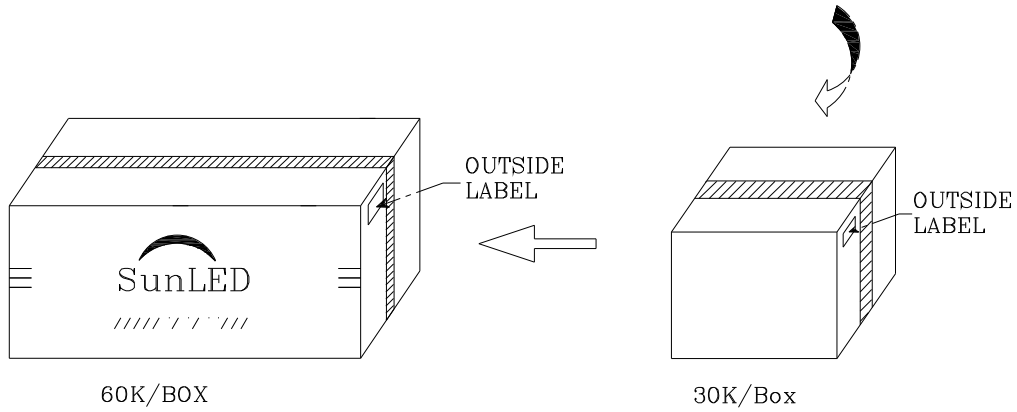
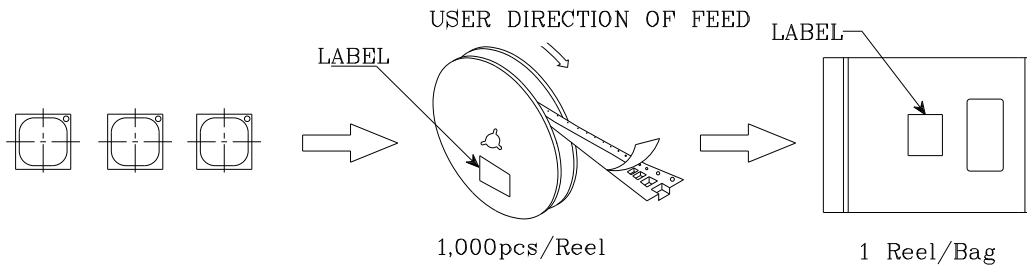
1. Wavelength: +/-1nm
2. Luminous intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V


Note: Accuracy may depend on the sorting parameters.



PACKING & LABEL SPECIFICATIONS

ZMEBGABBG86W



P/NO : Zxxx86x	
QTY : 1,000 pcs	CODE: XXX
S/N : XX	
LOT NO :	
 XXXXXXXXXXXXXXXXXXXXXXXXXXXX	
RoHS Compliant	